

## **SHENMAO Exhibits at SEMICON WEST July 11-13, 2017 Booth # 5716 Introduces New Low Residue Liquid Flux SMF-B51**



**SHENMAO Technology, Inc.** introduces New Generation Ultra Low Residue Liquid Flux **SMF-B51** with superior spray uniformity, excellent soldering performance and a wide process window for Chip Scale and Fan Out Wafer Level Packaging.

**SHENMAO** introduces New Generation Lead-free Solder Paste **PF606-P140** and Zero-Halogen Lead-free Solder Paste **PF606-P245** with a wide process window, superior print and solderability to solve Head on Pillow issues and improve ICT testability, easily fit into complicated PCB designs through excellent convergence performance.

**SHENMAO** BGA Solder Spheres for PBGA, CBGA, TBGA, CSP and Flip Chip Assemblies are made by UMT (Ultra Micron Technology) from highly pure metals produced to various exact Alloy compositions using Piezoelectric Droplet Jet Technology in high volumes to accurate diameter uniformity, bright shiny surface finishes and high-quality sphericity. Various diameters (0.76, 0.65, 0.64, 0.5, 0.45, 0.4, 0.3, 0.25, 0.2, 0.15, 0.1, 0.09, 0.08, 0.075, 0.07, 0.06, 0.055 and 0.05 mm Dia.- 0.045 and 0.040 mm Dia. are in development) are available in SAC305, SAC405 and SAC1205 Alloys at affordable low cost from 10 worldwide **SHENMAO** locations.

As the World's Major Solder Materials Provider, **SHENMAO** produces SMT Solder Paste, Wave Solder Bar, Cored Solder Wire and Flux, Solder Preforms, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.

For more information, please contact:

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